

Semiconductor Industry Energy Efficiency Scaling (EES2) Roadmap Working Group Meeting #9

Hosted by the DOE/EERE Advanced Materials and Manufacturing Technologies Office (AMMTO)

Virtual
August 16th-17th, 2023

AGENDA

Aug 16th, 12:00 PM – 4:45 PM EDT	
Time	Activity
12:00 – 1:45	Opening Plenary
12:05 – 12:15	Welcome from DOE AMO Organizer (Tina Kaarsberg, DOE AMMTO, Meeting Chair)
12:15 – 12:30	Pledge Signing Ceremony
12:30 – 1:00	Metrology and Benchmarking Group update (Jim Booth, NIST)
1:00 – 1:30	Computing Energy Efficiency (Sadas Shankar, Slac/Stanford)
1:30 – 1:35	Roadmap Strategy-Emmanuel Taylor
1:35 – 1:45	Break
1:45 – 3:35	Facilitated Discussions
1:45 – 3:00	Parallel Session 1: Circuits and Architectures, Power and Control, Metrology and Benchmarking, Manufacturing Energy Efficiency and Sustainability
3:00 – 3:10	Break
3:10 – 4:25	Parallel Session 2: Material and Devices, Software and Algorithms, Advanced Packaging/Heterogeneous Integration, Manufacturing Energy Efficiency and Sustainability
4:25 – 4:30	Day 2 Expectations
4:30 – 4:45	Day 1 Closing Remarks (Tina Kaarsberg, DOE AMMTO, Meeting Chair)

Aug 17th, 12:00 PM – 4:25 PM CDT	
Time	Activity
12:00 – 1:40	Opening Plenary
12:05 – 12:15	Welcome from DOE AMO Organizer (Tina Kaarsberg, DOE AMMTO, Meeting Chair)
12:15 – 12:45	Photonics overview (Dr Volker Sorger, Director of Florida Semiconductor Institute)

12:45 – 1:15	Energy Efficient ASICs (tbd)
1:15 – 1:20	Roadmap Strategy-Emmanuel Taylor
1:20 – 1:30	Break
1:30 – 4:10	Facilitated Discussions
1:30 – 2:45	Parallel Session 1: Advanced Packaging and Heterogeneous Integration, Algorithms and Software, Materials and Devices
2:45 – 2:55	Break
2:55 – 4:15	Parallel Session 1: Advanced Packaging and Heterogeneous Integration, Algorithms and Software, Materials and Devices
4:10 – 4:25	Day 2 Closing Remarks (Tina Kaarsberg, DOE AMMTO, Meeting Chair)